

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L18	2	((("7338822") or ("20080164480")).PN.	US-PGPUB; USPAT	OR	OFF	2010/09/10 09:43
L19	3	((("3897627") or ("6020261") or ("20030189212")).PN.	US-PGPUB; USPAT	OR	OFF	2010/09/10 09:45
S1	2	"US 20080210970"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/10/07 14:22
S2	2783	"257/99".CCLS.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S3	2183	"438/22".CCLS.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S4	56	"257/E33.063".CCLS.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S5	2749	"257/103".CCLS.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S6	4	((XUEJUN) near2 (KANG)). INV.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S7	2	((DAIKE) near2 (WU)). INV.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S8	119	((EDWARD) near2 (PERRY)). INV.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S9	55	((SHU) near2 (YUAN)). INV.	US-PGPUB; USPAT	OR	ON	2009/10/07 14:23
S10	172	S6 S7 S8 S9	US-PGPUB; USPAT	OR	ON	2009/10/07 14:24
S15	19	(light adj emit\$5) and (electroplat\$4 with ((heat adj sink) metal) with ohmic)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/03/25 14:12
S16	48	("5008718" "5376580" "5391257" "5646067" "5789320" "5807783" "6033925" "6046065" "6100166" "6194245" "6258699" "6287882"). PN. OR ("6468824"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/25 14:21

S17	43	("20010042866" "3869637" "5103271" "5185288" "5376580" "5793062" "5828088" "5917202" "6107648" "6222207" "6319778" "6365951" "6462358" "6469324" "6480389"). PN. OR ("6649437"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/25 14:22
S18	1	("6649437").PN.	US-PGPUB; USPAT	OR	OFF	2010/03/25 14:26
S19	65	S16 S17	US-PGPUB; USPAT	OR	ON	2010/03/25 14:27
S20	40	("20010055324" "20020022286" "20020034835" "20020093023" "20020113279" "20020137243" "20030064535" "20030189215" "20040065889" "20040110395" "20040235210" "20050098792" "20060099730" "20060151801" "20060154390" "20060154391" "20060154392" "20060154393" "20060157721" "4107720" "5192987" "5405804" "5654228" "6091085" "6169297" "6210479" "6303405" "6307218" "6365429" "6420242" "6420732" "6426512" "6448102" "6492661" "6562648" "6573537" "6627921" "6649437" "6677173" "6821804").PN.	US-PGPUB; USPAT	OR	ON	2010/03/25 14:27
S21	13	("5242840" "5300788" "5453405" "5744828"). PN. OR ("6319778"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/25 14:53

S22	21	("20010019134" "20020185648" "20030087463" "20030143772" "20030164503" "20030173602" "20030178637" "4963508" "5376580" "5391257" "5406575" "5502316" "6169296" "6258699" "6465809" "6468824" "6542528" "6716654").PN. OR ("6786390").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/25 15:02
S23	34	S21 S22	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/25 15:12
S24	2	"US 20030189215"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/03/25 15:19
S25	4	((XUEJUN) near2 (KANG)). INV.	US-PGPUB; USPAT	OR	ON	2010/03/25 15:20
S26	2	((DAIKE) near2 (WU)). INV.	US-PGPUB; USPAT	OR	ON	2010/03/25 15:20
S27	121	((EDWARD) near2 (PERRY)).INV.	US-PGPUB; USPAT	OR	ON	2010/03/25 15:20
S28	64	((SHU) near2 (YUAN)). INV.	US-PGPUB; USPAT	OR	ON	2010/03/25 15:20
S29	183	S25 S26 S27 S28	US-PGPUB; USPAT	OR	ON	2010/03/25 15:20
S30	5	S29 and (light adj emi\$5) and electroplat\$3	US-PGPUB; USPAT	OR	ON	2010/03/25 15:20
S31	18	(ohmic near2 (layer contact)) with ((seed wetting) adj layer) with ((conductive metal) adj (substrate layer))	US-PGPUB; USPAT	OR	ON	2010/03/26 10:27
S32	21	("20010019134" "20020185648" "20030087463" "20030143772" "20030164503" "20030173602" "20030178637" "4963508" "5376580" "5391257" "5406575" "5502316" "6169296" "6258699" "6465809" "6468824" "6542528" "6716654").PN. OR ("6786390").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 10:51

S33	43	("20010042866" "3869637" "5103271" "5185288" "5376580" "5793062" "5828088" "5917202" "6107648" "6222207" "6319778" "6365951" "6462358" "6469324" "6480389"). PN. OR ("6649437"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 10:51
S34	13	("5242840" "5300788" "5453405" "5744828"). PN. OR ("6319778"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 10:51
S35	73	S32 S33 S34	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 10:53
S36	3756	(light adj emi\$5) and ((seed wetting) with layer)	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:08
S37	8104	((seed wetting) with layer) with (metal near2 (layer substrate))	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:09
S38	489	S37 and (light adj emi\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:09
S39	1786	((seed wetting) with layer) with (metal near2 (layer substrate)) with (electroplat\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:12
S40	75	S39 and (light adj emi\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:12
S41	111	(light adj emit\$5) and (electroplat\$4 with (metal near2 (layer substrate)) (heat adj sink)) with (seed wetting)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/03/26 11:18
S42	76	(light adj emit\$5) and (electroplat\$4 with ((metal near2 (layer substrate)) (heat adj sink))) with (seed wetting)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/03/26 11:22
S43	4090	(electroplat\$4 same ((metal near2 (layer substrate)) (heat adj sink))) same (seed wetting)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/03/26 11:56
S45	184	S43 and (light adj emi\$5)	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:57
S46	109	S45 not S42	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 11:57

S47	4	("5385632" "5776512"). PN. OR ("6812067"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/26 12:09
S48	992	((seed\$3 wett\$3) near2 layer) with electro\$1plat \$3 with (metal adj (substrate layer))	US-PGPUB; USPAT	OR	ON	2010/03/26 12:24
S49	300	S48 and light	US-PGPUB; USPAT	OR	ON	2010/03/26 12:24
S50	34	S48 and (light adj emi\$5)	US-PGPUB; USPAT	OR	ON	2010/03/26 12:32
S51	1	(ohmic adj electrode) with 10nm	US-PGPUB; USPAT	OR	ON	2010/03/26 17:50
S52	1050	((seed\$3 wett\$3) near2 layer) with electro\$1plat \$3 with (metal adj (substrate layer))	US-PGPUB; USPAT	OR	ON	2010/09/09 17:52
S53	38	S52 and (ohmic)	US-PGPUB; USPAT	OR	ON	2010/09/09 17:53
S54	3637	((seed\$3 wett\$3) near2 layer) same electro\$1plat \$3 same ((copper metal) adj (substrate layer contact plug))	US-PGPUB; USPAT	OR	ON	2010/09/09 17:57
S55	333	S54 and (epitaxial)	US-PGPUB; USPAT	OR	ON	2010/09/09 17:58
S56	74	S54 and (epitaxial and ohmic)	US-PGPUB; USPAT	OR	ON	2010/09/09 17:58
S57	24	("20030089958" "20050051859" "4491983" "5049521" "5973337" "6143588" "6348682" "6483101" "6521476" "6586721" "6614103" "6633421" "6686580" "6703689" "6737720").PN. OR ("7038288").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 18:18
S58	8	("20050045901" "20050072835" "20050184387" "20060138444" "5777433" "6274924" "6486499").PN. OR ("7348212").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 18:20

S59	61	("3813587" "4238707" "4329625" "4423478" "4983884" "5362977" "5408120" "5410159" "5461425" "5557115" "5563422" "5744829" "5862167" "5886401" "5914501" "5998232" "6016038" "6081540" "6091085" "6121127" "6133589" "6150774" "6169294" "RE36747"). PN. OR ("6486499"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 18:22
S60	17243	(light adj emitt\$3) and (remov\$3 near3 substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 18:35
S61	216	S60 and (ohmic adj contact) and (electroplat \$3)	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 18:35
S62	17	("6091085" "6287882"). PN. OR ("6555405"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 18:48
S63	59	adhesive with electroplating with seed	US-PGPUB; USPAT	OR	ON	2010/09/09 19:07
S64	43	adhesive with electroplating with seed with (metal copper)	US-PGPUB; USPAT	OR	ON	2010/09/09 19:07

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